641.

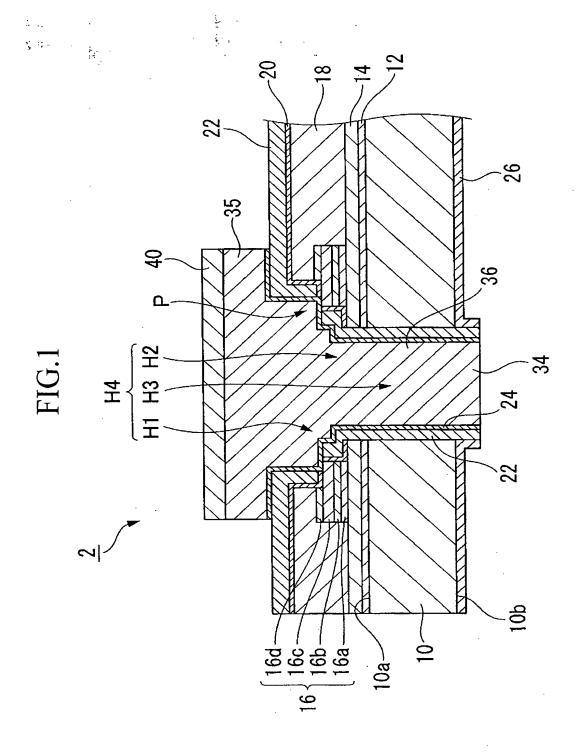
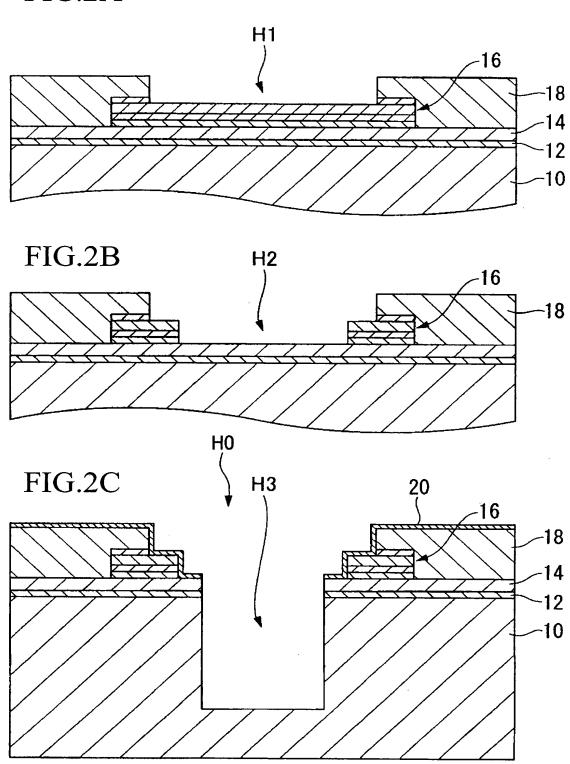
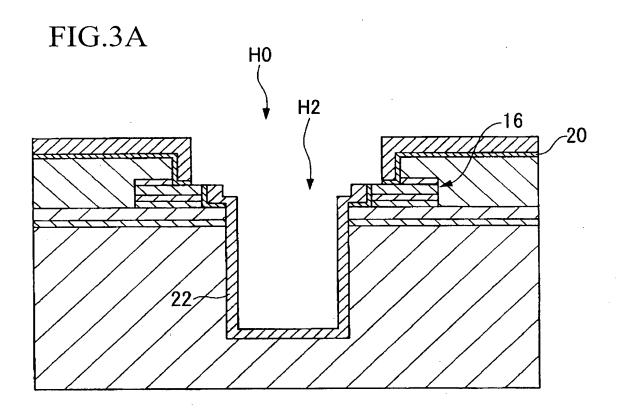
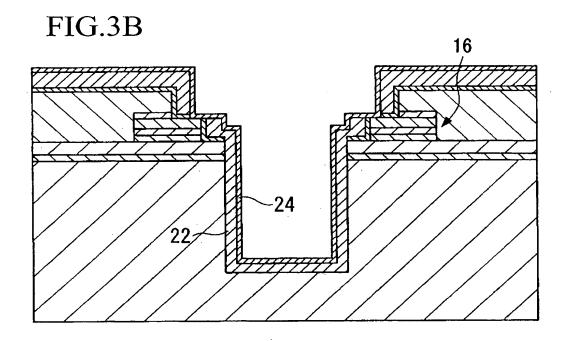


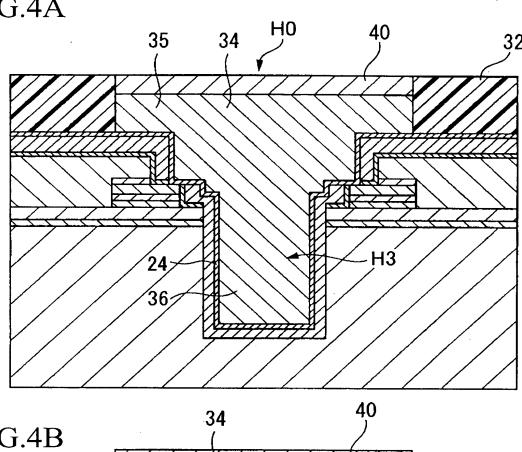
FIG.2A











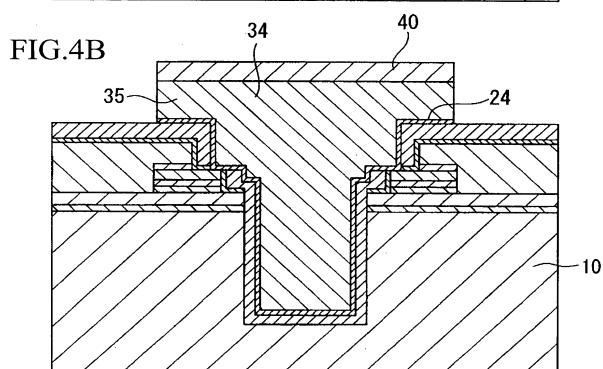


FIG.5A

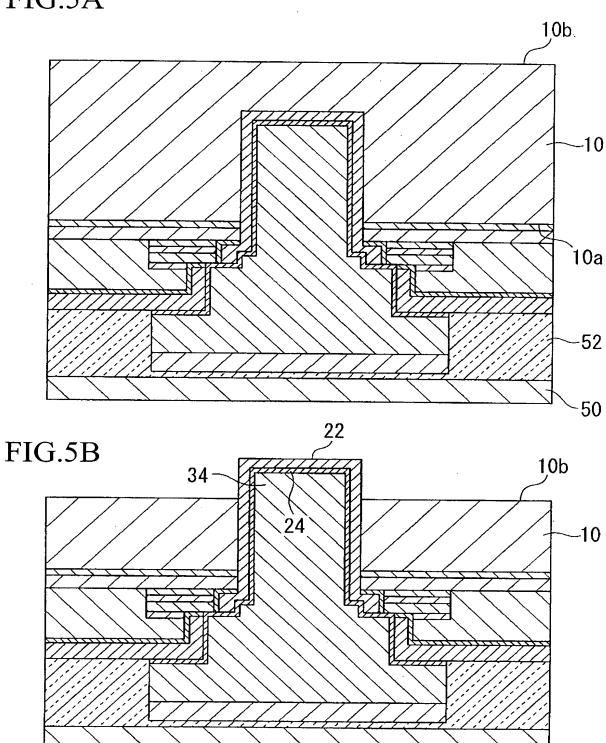
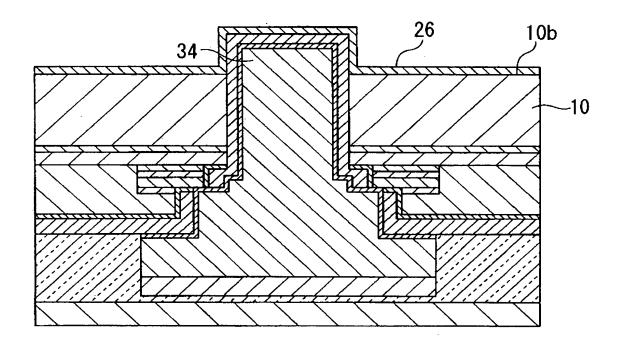


FIG.6A



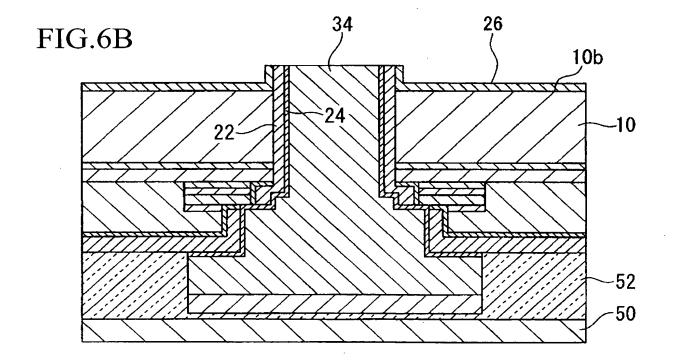
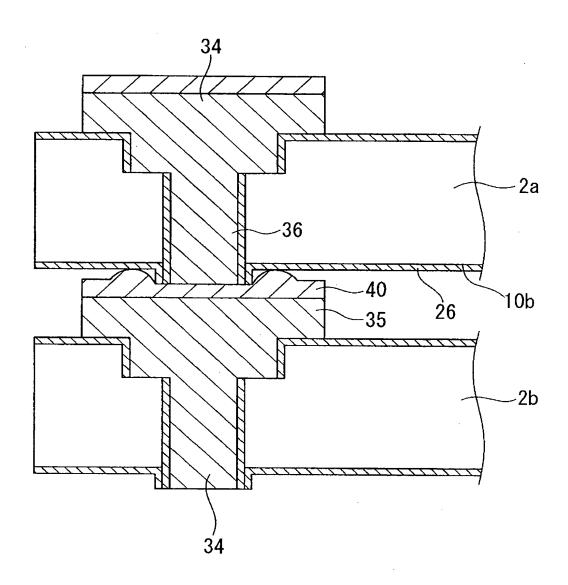


FIG.7



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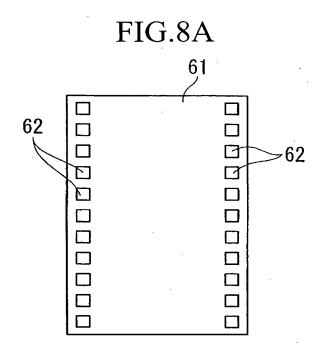


FIG.8B

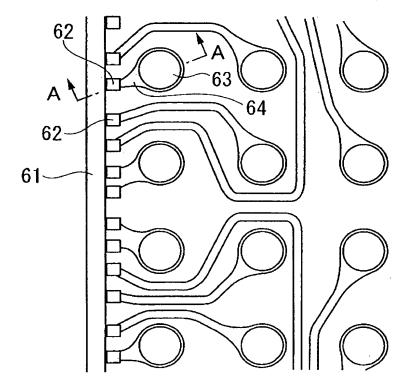


FIG.9

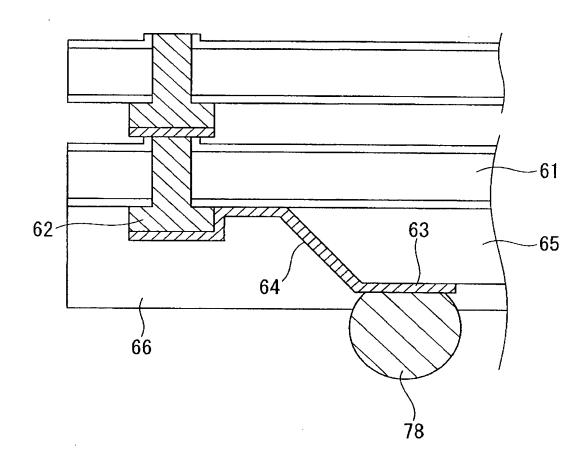
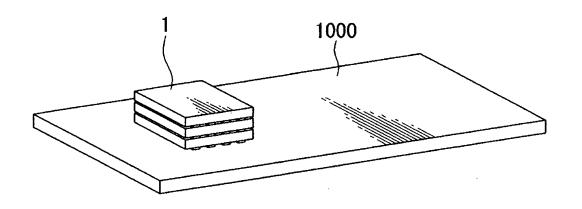


FIG.10

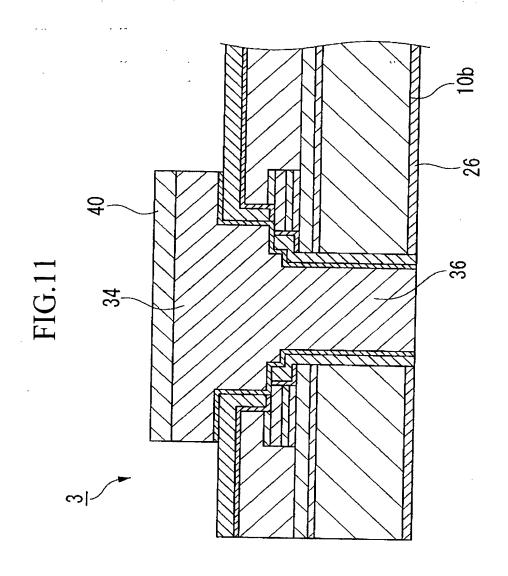


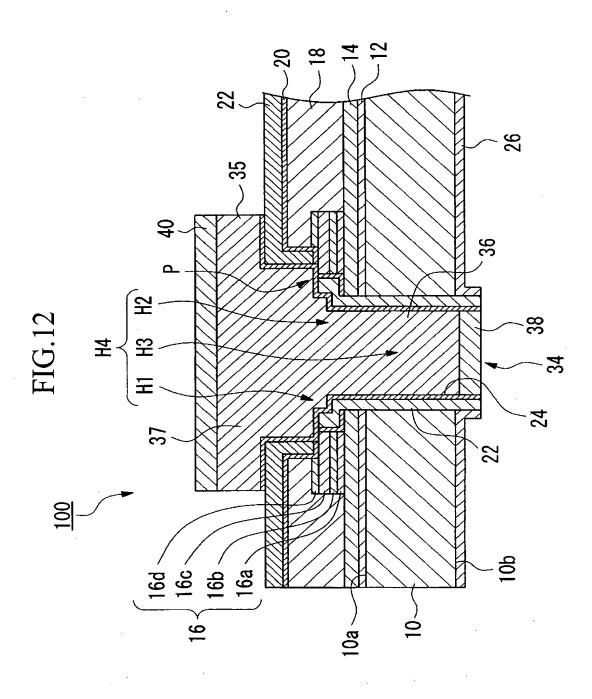
Title: METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE, SEMICONDUCTOR DEVICE, CIRCUIT SUBSTRATE AND ELECTRONIC APPARATUS Inventor(s): Ikuya MIYAZAWA
Atty. Ref.: 9319G-000739

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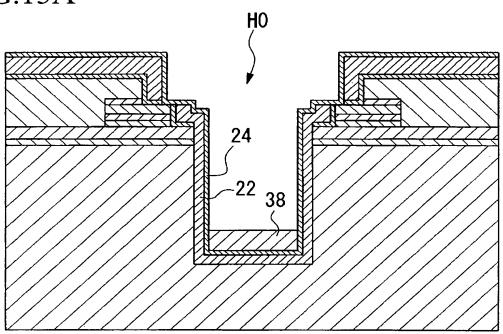
1.29

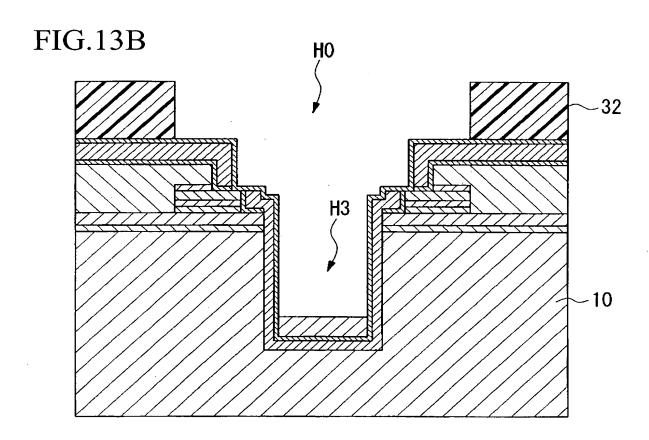




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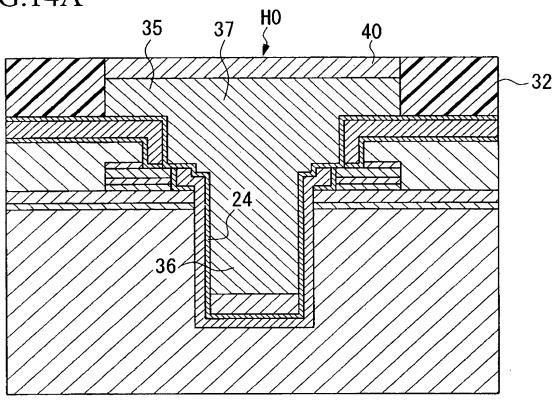
FIG.13A

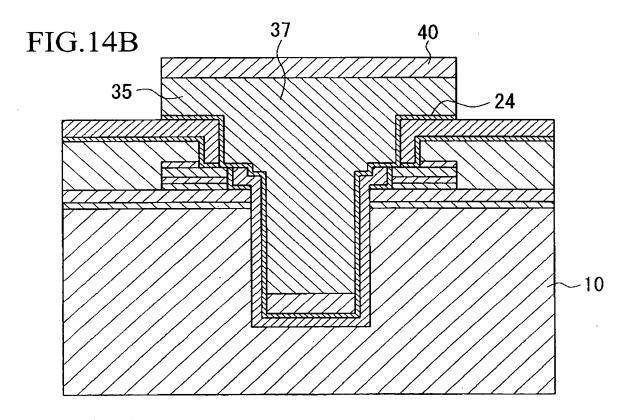




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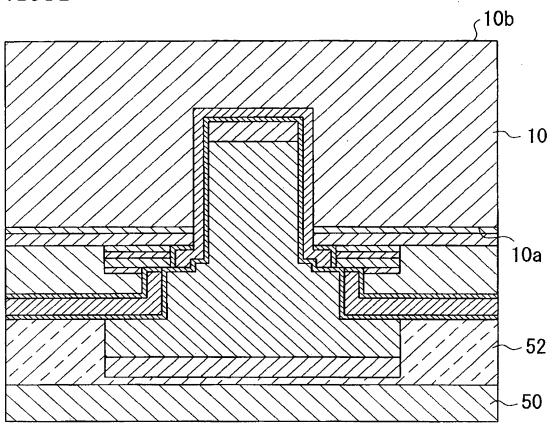


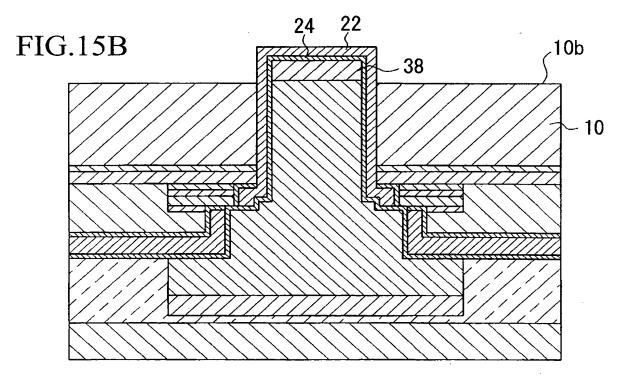


Atty. Ref.: 9319G-000739

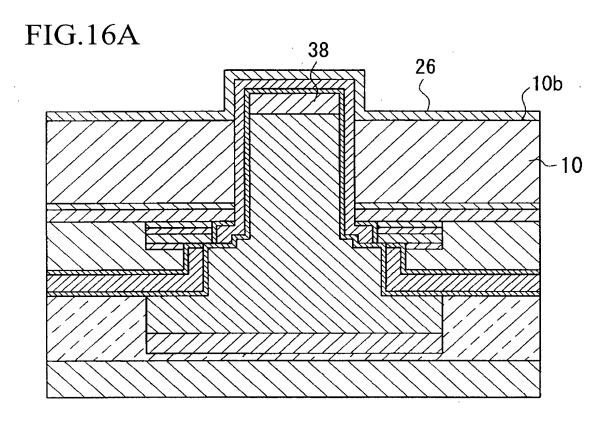
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FIG.15A





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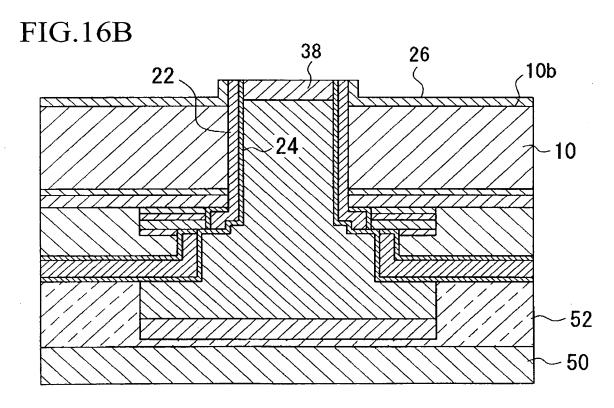
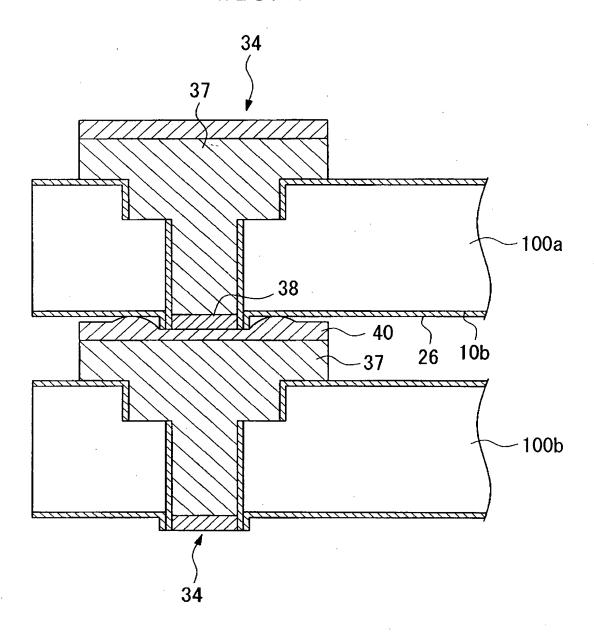
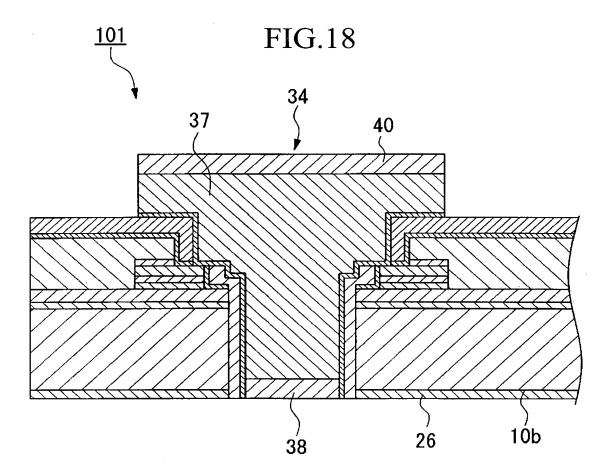


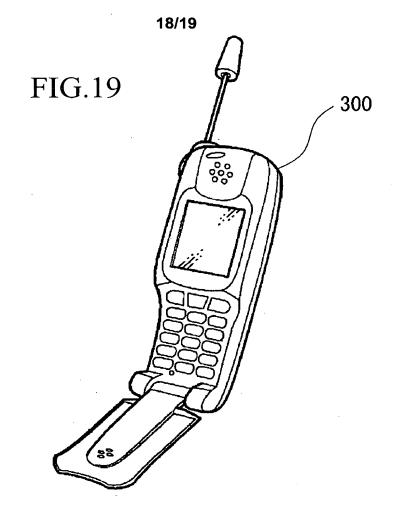
FIG.17

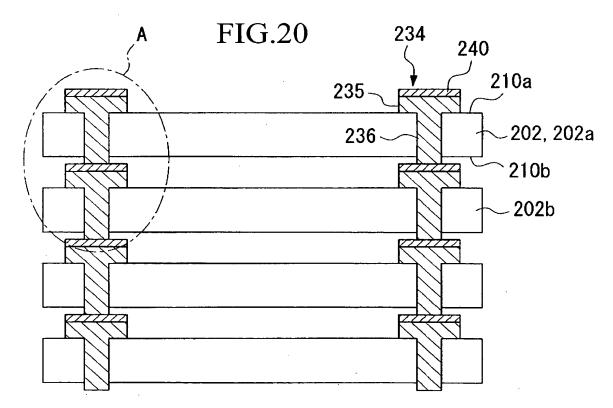


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## Title: METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE, SEMICONDUCTOR DEVICE, CIRCUIT SUBSTRATE AND ELECTRONIC APPARATUS





Title: METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE, SEMICONDUCTOR DEVICE, CIRCUIT SUBSTRATE AND ELECTRONIC APPARATUS

Inventor(s): Ikuya MIYAZAWA Atty. Ref.: 9319G-000739

FIG.21

